

ABSTRACT

A composition for pressure bonding of the present invention contains a metal powder and a solid reducing agent and has a compressibility of 10% to 90%, the compressibility being expressed by a relationship formula using the thickness A of a dried coating film formed by drying the composition in an air atmosphere at 110°C under atmospheric pressure for 20 minutes and the thickness B of a sintered body formed by treating the dried coating film in a nitrogen atmosphere at 280°C under a pressure of 6 MPa for 20 minutes. It is also preferable that the solid reducing agent is BIS-TRIS. Also provided is a bonded structure of conductors in which a bonding portion via which two conductors are bonded together is formed by treating, under pressure, the two conductors and a coating film formed of the composition for pressure bonding provided therebetween.